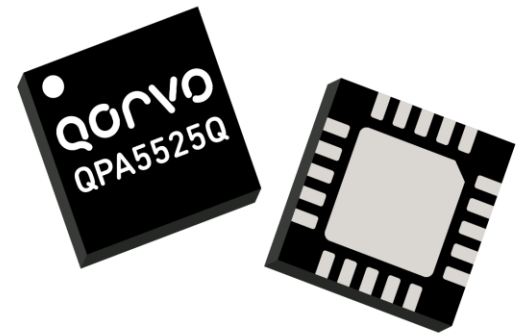


QPA5525Q

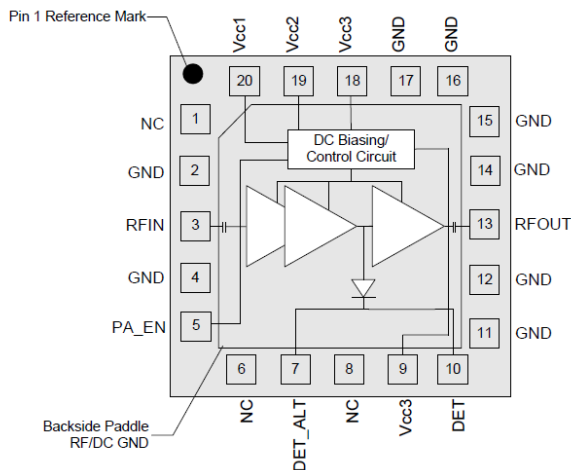
802.11ac/p Power amplifier

The QPA5525Q is power amplifier module containing an internally matched 3-stage PA, compensated DC biasing circuit and output power detector. This PA module provides high gain (32 dB), high linearity, industry leading EVM floor, and excellent spectral purity for 802.11p applications.

The QPA5525Q features chipset logic compatible control voltages and buffered PA enable pin (PAEN) all of which draw very low current to facilitate ease of use and compatibility with current and future transceiver generations. The QPA5525Q is assembled in a small footprint 4.0 x 4.0 x 0.85 mm 20-pin QFN package.



Package: QFN, 20-pin,
4mm x 4mm x 0.85mm



Functional Block Diagram

Ordering Information

| | |
|----------------|---|
| QPA5525QSB | Standard 5-piece Sample Bag |
| QPA5525QSQ | Standard 25-piece Sample Bag |
| QPA5525QSR | Standard 100-piece Reel |
| QPA5525QTR7 | Standard 750-piece Reel |
| QPA5525QTR13 | Standard 2500-piece Reel |
| QPA5525QPCK401 | Fully Assembled Evaluation Board + 5-piece Sample Bag |

Revision DS Rev H

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Features

- Tested in accordance with AEC-Q100 Grade 2
- Internally Matched Input/Output
- High Gain = 32dB
- Integrated CMOS Compatible Logic and Shutdown
- Supply Voltage: +3.15 V to +5.25 V
- Typ. P_{OUT} = +26 dBm, Class C Spectral Mask 802.11p

Leadless 4.0 x 4.0 x 0.85 mm Pb-Free QFN Package

Applications

- 802.11ac/p Systems
- Automotive WiFi

Disclaimer: Subject to change without notice

www.qorvo.com

Absolute Maximum Ratings

| Parameter | Rating | Unit |
|---|-------------|-----------------|
| DC Supply Voltage (No RF applied) | +6.0 | V _{DC} |
| Operating Ambient Temperature | -40 to +105 | °C |
| Storage Temperature | -40 to +150 | °C |
| Maximum TX Input Power into 50Ω Load, CW, T= 25°C | +5 | dBm |



Caution! ESD sensitive device.



RFMD Green: RoHS status based on EU Directive 2011/65/EU (at time of this document revision), halogen free per IEC 61249-2-21, < 1000ppm each of antimony trioxide in polymeric materials and red phosphorus as a flame retardant, and <2% antimony in solder.

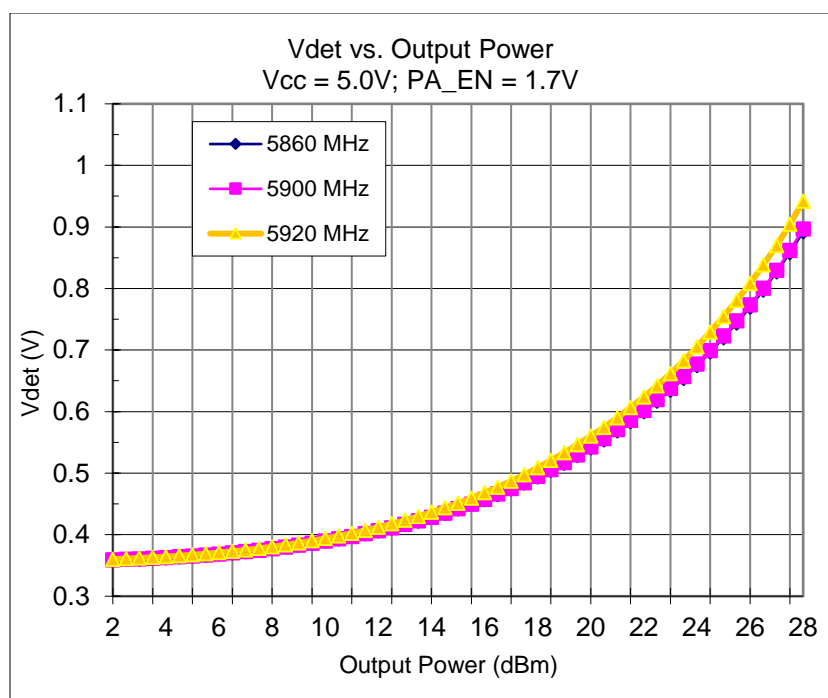
Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

Nominal Operating Parameters

| Parameter | Specification | | | Unit | Condition |
|---|---------------|-------|-------|---------|--|
| | Min | Typ | Max | | |
| Compliance | | | | | IEEE802.11a/n/ac/p |
| Operating Frequency | 5.15 | | 5.925 | GHz | |
| Operating Ambient Temperature | -40 | 25 | +105 | °C | |
| Power Supply V _{CC} ¹ | 3.15 | 5.0 | 5.25 | V | V _{CC1} = V _{CC2} = V _{CC3} |
| T _j (for >10 ⁶ hours MTTF) | | | +170 | °C | |
| Transmit Performance | | | | | T=+25°C, V_{CC}= 5V, PA_EN = 1.7V; Unless otherwise noted |
| 11p Linear output Power | | +26 | | dBm | 802.11p, 5900MHz, 10MHz BW, M7, 27Mbps, 64QAM, 50% DC |
| 11p DEVM | | 2.8 | 4.0 | % | |
| | | -31 | -28 | dB | |
| 11ac Linear output Power | | +24 | | dBm | 802.11ac MCS9, 80MHz BW, 50% DC |
| 11ac DEVM | | 1.3 | 2.0 | % | |
| | | -38 | -34 | dB | |
| Operational Current | | 640 | 750 | mA | 26dBm, 802.11p, 10MHz BW, M7, 50% DC |
| | | 545 | 675 | mA | 24dBm, 802.11ac, 80MHz BW, MCS9, 100% DC |
| Input Return Loss | | 10 | | dB | |
| Output Port Return Loss | | 10 | | dB | |
| 2 nd Harmonics @ 27.5dBm | | -45 | | dBm/MHz | P _{out} = 27.5dBm, measured with a standard IEEE 802.11p waveform |
| 3 rd Harmonics @ 27.5dBm | | -45 | | dBm/MHz | P _{out} = 27.5dBm, measured with a standard IEEE 802.11p waveform |
| Small Signal Gain | 29 | 32 | 36 | dB | |
| OP1dB | | +31 | | dBm | Measured with CW |
| OIP3 | | +36 | | dBm | P _{out} = +12dBm/Tone, 1 MHz spacing, f ₀ = 5860 MHz |
| Power Detector Voltage | | +0.37 | | V | No RF |
| | | +0.69 | | | P _{out} = +24dBm, F ₀ = 5855 MHz |
| Spectral Emission Mask Margin relative to IEEE 802.11p standard (Class C) | 0 | -2 | | dB | 5900MHz, 10 MHz BW, M0; P _{out} =26dBm @ +25C |

| Parameter | Specification | | | Unit | Condition |
|-------------------------------------|---------------|-------|------------------|------|--|
| | Min | Typ | Max | | |
| | | | | | |
| General Specifications | | | | | T=+25°C, V_{CC}= 5V, Unless otherwise noted |
| Quiescent Current | | 350 | | mA | |
| TX Shutdown Current | | 10 | | μA | PA_EN = Low, No RF |
| PA Enable Current | | 20 | | μA | |
| PA Enable Voltage – High State | 1.7 | 3.0 | V _{CC1} | V | |
| PA Enable Voltage – Low State | | 0.00 | 0.45 | V | |
| Switch Speed | | 400 | | nS | |
| Thermal Resistance, θ _{jb} | | 20.22 | | °C/W | Junction to Board |

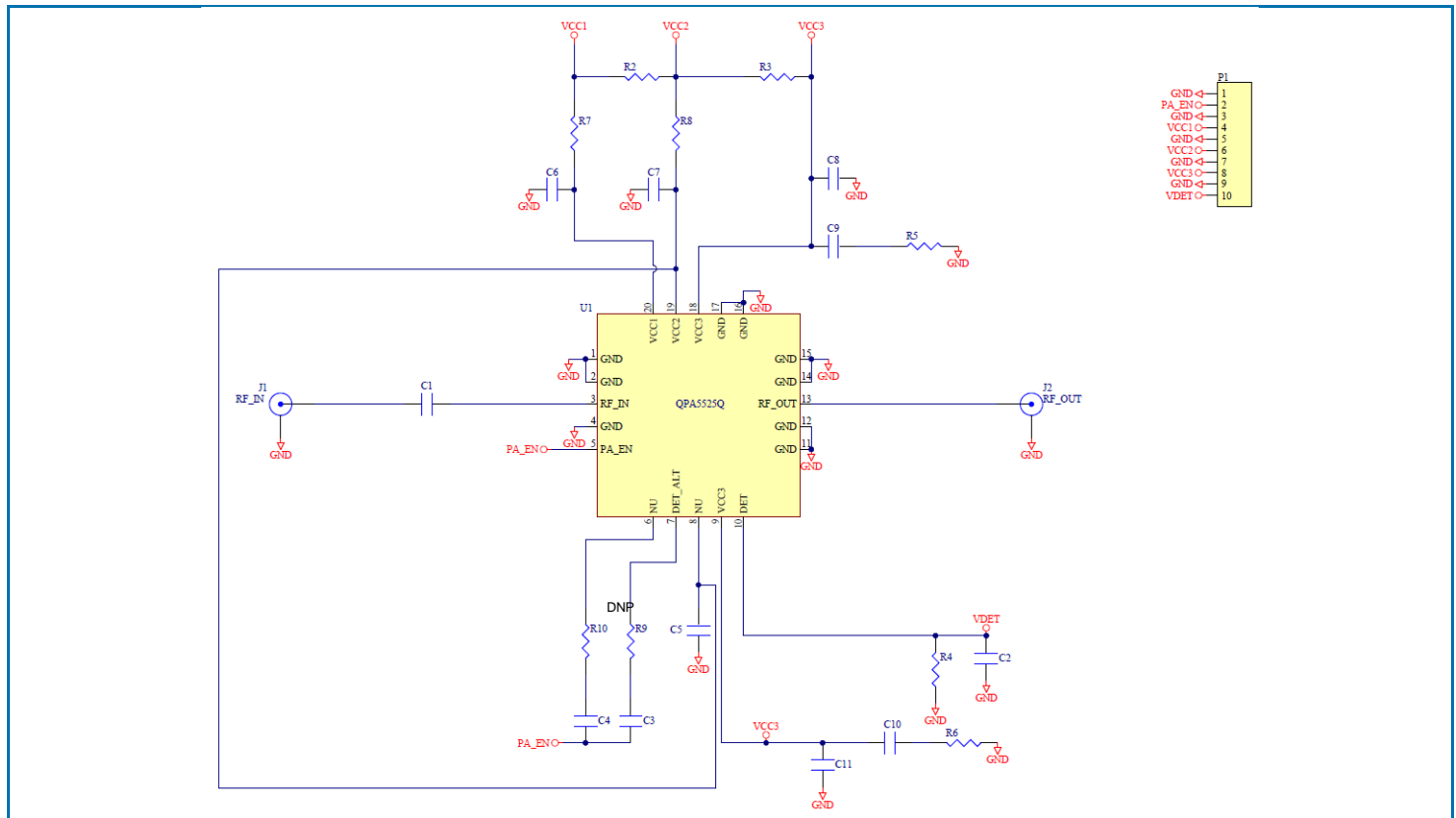
¹ RF performance degrades as V_{CC} is lowered <5.0V



Control Logic Truth Table

| PA Mode | PA_EN |
|----------|-------|
| Disabled | Low |
| Enabled | High |

Applications Schematic

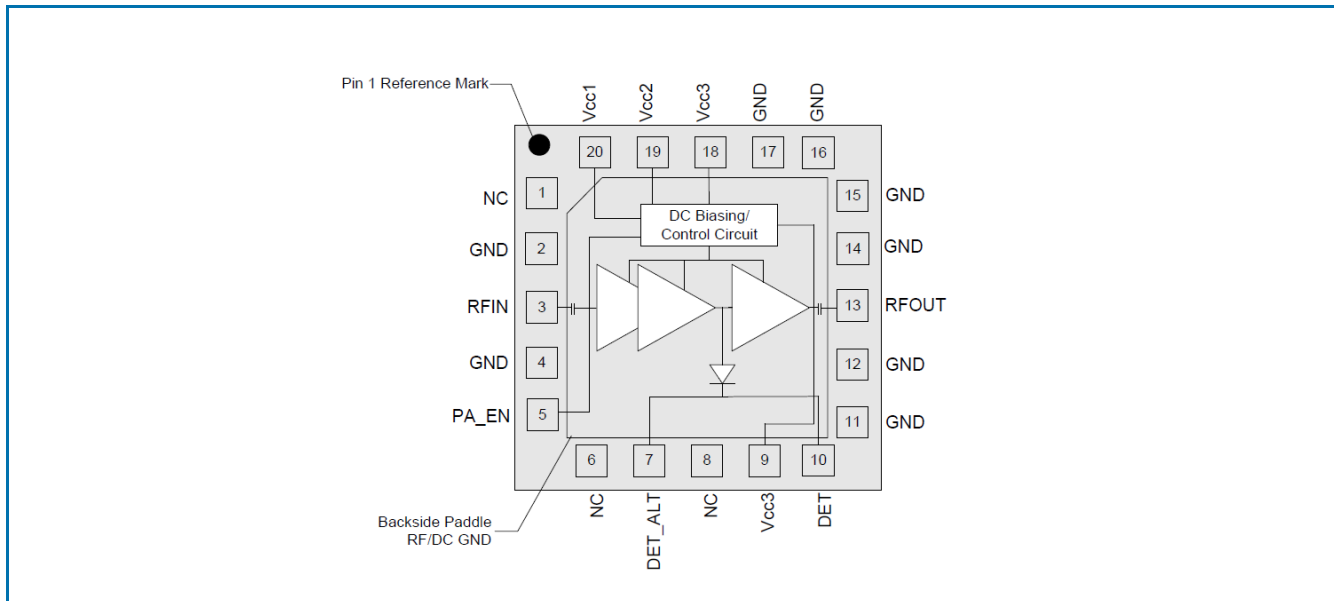


Bill of Material

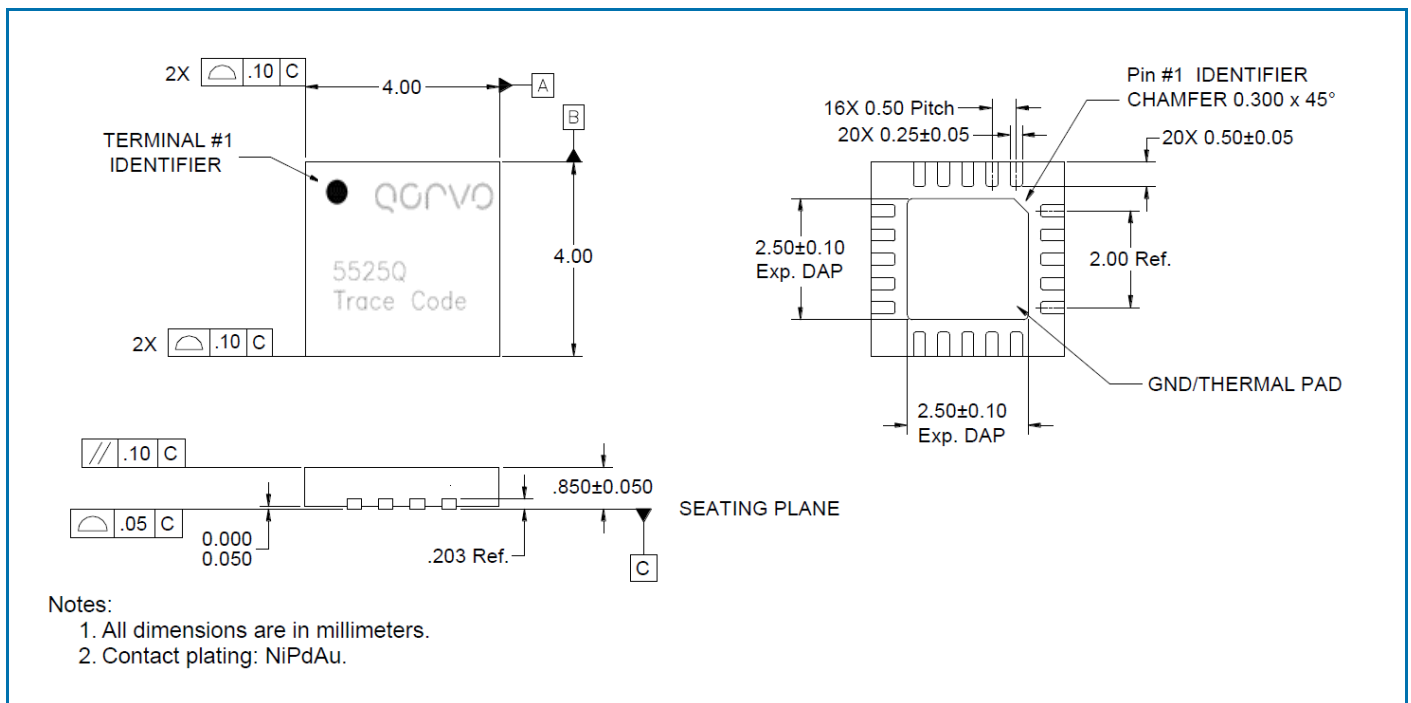
| Material# | Rev | Qty | Ref Des | Description |
|-----------------|-----|-----|-----------|--|
| QPA5525QSB | B | 1 | U1 | 5GHz High Power PA |
| 284511 | A | 1 | | PCB, QPA5525Q |
| 1099541 | | 1 | | PCB, WLAN PA |
| 21714 | | 3 | C2,C9,C10 | CAP, 220pF, 10%, 50V, X7R, 0402 |
| 21730 | | 2 | C6,C7 | CAP, 0.1uF, 10%, 10V, X5R, 0402 |
| 264344 | | 1 | C1 | CAP, 10pF, 5%, 50V, CG, 0402 |
| 278575 | A | 2 | C8,C11 | CAP, 10uF, 20%, 10V, STD, 0603 |
| 010-0405-02R0LF | | 2 | R5,R6 | Res0402 2 ohm ROHS |
| 1067980 | | 1 | R4 | 863000-027 RES0402 27.4K 1PCT 1/16W |
| 21592 | | 3 | R2,R3,R8 | RES, 0 OHM, 5%, 1/10W, 0402 |
| 43268 | | 1 | R7 | RES, 27 OHM, 5%, 1/16W, 0402 |
| 23674 | | 1 | P1 | CONN, HDR, ST, PLRZD, 10-PIN, 0.100" |
| 46006 | | 2 | J1,J2 | CONN, SMA, END LNCH, RND, 0.062" |
| 1069007 | | 1 | HS1 | 452500-001 FAB. BLOCK, MOUNTING |
| 1068796 | | 4 | | 850000-703 WASHER. FLAT. #2. SMALL. SS |
| 1069247 | | 4 | | 860000-597 SCREW. MCH. PAN. XR. 2-56. 0. |
| 1069257 | | 4 | | 034031-000 WASHER. SPLIT. #2. MEDIUM. SS |
| 4XXX1 | | 3 | C3,C4,C5 | NOT POPULATED ITEM-1 |
| 4XXX2 | | 2 | R9,R10 | NOT POPULATED ITEM-2 |

Each EVB is shipped with a heat sink mounted to backside of PCB.

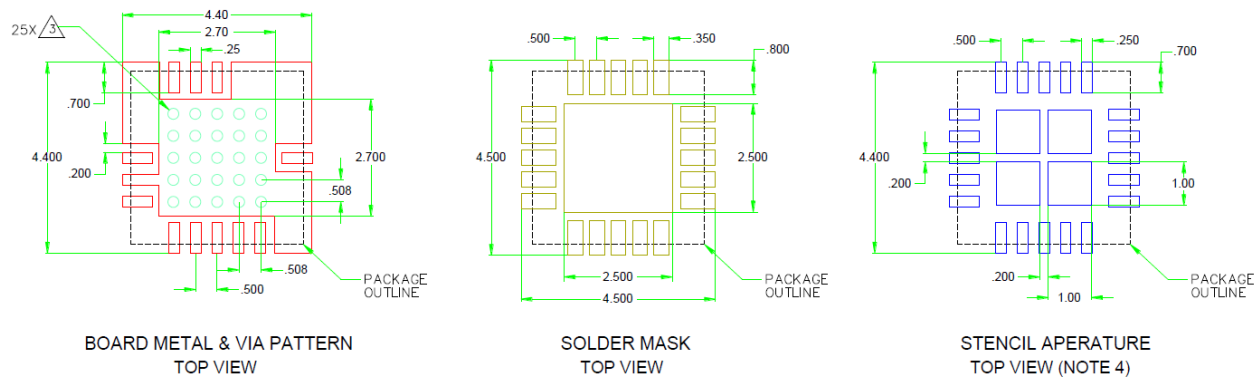
Pin Out



Package Drawing



PCB Patterns



Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layer metal.
3. Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25 mm (0.10").
4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.

Pin Names and Descriptions

| Pin | Name | Description |
|-----------------|-----------|--|
| 1 | NC | No internal connection. This pin can be grounded or N/C on PCB. |
| 2 | GND | Ground |
| 3 | RF_IN | RF Input |
| 4 | GND | Ground |
| 5 | PA_EN | PA Enable |
| 6 | NC | No internal connection. This pin can be grounded or N/C on PCB. |
| 7 | DET_ALT | Alternate Detector Output |
| 8 | NC | No internal connection. This pin can be grounded or N/C on PCB. |
| 9 | VCC3 | Supply voltage for third stage PA |
| 10 | DET | Detector Output |
| 11 | GND | Ground |
| 12 | GND | Ground |
| 13 | RF_OUT | RF Output |
| 14 | GND | Ground |
| 15 | GND | Ground |
| 16 | GND | Ground |
| 17 | GND | Ground |
| 18 | VCC3 | Supply voltage for third stage PA |
| 19 | VCC2 | Supply voltage for second stage PA |
| 20 | VCC1 | Supply voltage for first stage PA |
| Backside Paddle | RF/DC GND | FEM RF/DC ground. Use recommended via pattern to minimize inductance and thermal resistance. See PCB Mounting Pattern for suggested footprint. |

Product Compliance Information

ESD Sensitivity Ratings



Caution! ESD-Sensitive Device

ESD Rating: Class 1B
Value: Passes ≥ 500 V to < 1000 V
Test: Human Body Model (HBM)
Standard: JEDEC Standard JESD22-A114

ESD Rating: Class C2
Value: Passes ≥ 500 V to < 1000 V Test:
Charged Device Model (CDM)
Standard: JEDEC Standard JESD22-C101

MSL Rating

MSL Rating: Level 2
Test: 260°C convection reflow
Standard: JEDEC Standard IPC/JEDEC J-STD-020

Solderability

Compatible with both lead-free (260°C max. reflow temperature) and tin/lead (245°C max. reflow temperature) soldering processes.

Package contact plating: NiPdAu

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

RoHS Compliance

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A ($\text{C}_{15}\text{H}_{12}\text{Br}_4\text{O}_2$) Free
- PFOS Free
- SVHC Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Tel: 1-844-890-8163

Web: www.qorvo.com

Email: customer.support@qorvo.com

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